

Revised
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TECHNICAL DATA SHEETS
MP 5471

Description:

MP 5471 is a clear, two part unfilled electronics grade epoxy resin system. It was designed for applications where fast cure and excellent high temperature thermal stability is required. It cures very quickly at room temperatures to a tough, rigid polymer. It has good wetting and adhesion to most surfaces and has a free-flowing viscosity. It has excellent thermal stability and very good resistance to water, acids and bases and most organic solvents.

Typical Properties:

Color		Clear
Viscosity	Part A:	1,000cps
	Part B:	10,000cps
	Mixed	1,100cps
Specific Gravity	Part A:	1.16
	Part B:	1.12
	Mixed	1.16
Pot Life		60-75 seconds
Mass		5 grams
Temperature Range, °C:		-40 to 180
Hardness, (Instantaneous Reading):		85 Shore D
Tensile Elongation		3-4%
Tensile Strength:		8,500 psi
Dielectric Constant (25C, 100HZ)		3.5*
Dielectric Strength, Volt/Mil:		415 v/mil
Volume Resistivity, ohm-cm, 25°C:		8.3 x 10 ¹⁴ ohm-cm

Mix Ratio:

Mix Ratio (Part A to B):	
By weight	9.5 to 1
By volume	10 to 1

Shelf Life:

12 months

Cure Schedule:

24 hours at 25°C

Instructions:

1. Bring both components to room temperature prior to mixing.
2. If used in bulk, weigh and mix parts A and B accurately and thoroughly, scraping sides of container often. Do not pour from mixing container, transfer to a new container as residual unmixed material may cause a tacky spot on surface of casting.
3. Allow to cure undisturbed until product is fully gelled or tack-free to the touch
4. Clean up uncured resin with suitable organic solvent such as MEK, acetone or other organic solvent.

Engineering Excellence

For technical information
and support call **1-800-552-0299** or visit our website at

www.instantca.com